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Patent claims

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1. A conductor track supporting layer (1) for laminating inside a chip card (8) comprising at least one conductor track (2) which is applied to a conductor track supporting layer (1) by an application method, preferably a screen printing method, and consists of a conductive paste or high-viscosity liquid, and comprising connecting areas (3) which are connected to the conductor track (2), characterized in that the conductor track supporting layer (1) has in the region of the connecting areas (3) indentations (4a, 4b, 4c) which are filled with the paste or the high-viscosity liquid during the application operation.
  2. The conductor track supporting layer as claimed in claim 1, characterized in that the indentations (4a, 4b, 4c) are made as through-holes (6) with an opening (7) on the rear side (9) of the conductor track supporting layer, lying opposite the conductor track (2) of the supporting layer (1).

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3. The conductor track supporting layer as claimed in claim 2, characterized in that it is provided on the rear side (9) with a protective film (10).
4. The conductor track supporting layer as claimed in one of claims 1 to 3, characterized in that the conductor track (2) has the form and function of a coil. A
5. The conductor track supporting layer as claimed in one of claims 1 to 4, characterized in that the screen printing paste (5) has a silver particle content of from 70 to 80% percent by volume.
6. The conductor track supporting layer as claimed in claim 5, characterized in that the grain size of the silver particles is greater than 45  $\mu\text{m}$ .
7. The conductor track supporting layer as claimed in one of claims 1 to 6, characterized in that a plurality of sublayers (18, 19, 20) provided with through-holes (21) are stacked exactly in position one on top of the other and bonded to one another to form a common conductor track supporting layer
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(1), indentations (4a, 4b, 4c) of different depths being formed by making the positions of the through-holes (21) in the sublayers (18, 19, 20) coincide.

8. A chip card with a chip module (11), arranged in a recess (12) of the chip card body (16), and/or further electronic components, with a conductor track supporting layer (1), to which at least conductor tracks (2) consisting of a screen printing paste and connecting areas (3) connected to the conductor track (2) have been applied by a screen printing method, characterized in that the conductor track supporting layer (1) has in the region of the connecting areas (3) indentations (4) filled with screen printing paste, in that the recess (12) for the chip module (11) and/or further electronic components is arranged on the side of the conductor track supporting layer (1) not coated with the conductor track (2) and in that the recess (12) has such a depth that the bottom region reaches so far into the conductor track supporting layer (1) that the indentations (4a, 4b, 4c) filled

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with screen printing paste of the conductor track supporting layer (1) are exposed.

9. A method for producing a chip card, comprising a multilayer plastic card body (16), at least one electronic component, preferably a chip module (11), arranged in a recess (12) of the plastic card body (16), in which
- at least one conductor track supporting layer (1), at least two covering layers (14, 15) covering the conductor track supporting layer (1) on both flat sides are arranged exactly in position one on top of the other,
- the card layers (1, 14, 15) arranged one on top of the other are bonded to one another in a laminating press by the influence of pressure and heat,
- after removal of the plastic card body (16) from the laminating press, the recess (12) for the electronic component (chip module) (11) is milled into said body and
- subsequently, the component (11) for establishing an electrical connection with the connecting areas (2) on the conductor track supporting layer (1) is

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inserted into the recess (12) of the plastic card body (16),

characterized by

the making of indentations (4a, 4b, 4c) into the conductor track supporting layer (1) at predetermined locations for the placement of connecting areas (3),

the coating of the conductor track supporting layer (1) in an application method, preferably a screen printing method, with conductor tracks (2) and connecting areas (3) connected to the conductor tracks (2) consisting of screen printing paste in such a way that the paste or high-viscosity liquid used for the coating fills the indentations (4a, 4b, 4c) in the conductor track layer (1),

the milling-out of the recesses (12) for the electronic components (11) from the outer side of the plastic card body (16), which is remote from the side of the conductor track supporting layer (1) coated with conductor tracks, the recess (12) having such a depth that its bottom region reaches into the conductor track supporting layer (1) and the indentations (4a, 4b, 4c) filled with screen

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printing paste of the conductor track supporting layer (1) are exposed.

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10. The method as claimed in claim 9, characterized in that the depressions (4a, 4b, 4c) are punched into the conductor track supporting layer (1) as through-holes (6). A

11. The method as claimed in claim 10, characterized in that, after the punching-out of the holes (6), the conductor track supporting layer (1) is coated on one side with a protective film (10).

12. The method as claimed in claim 9, characterized in that a plurality of sublayers (18, 19, 20) provided with through-holes (21) are stacked exactly in position one on top of the other and bonded to one another to form a common conductor track supporting layer (1), indentations (4a, 4b, 4c) of different depths being formed by making the positions of the through-holes (21) in the sublayers (18, 19, 20) coincide.

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